Notes

No tracks or vias in the shaded keepout area.

No other track or signal within 0.020" of any contact pad.

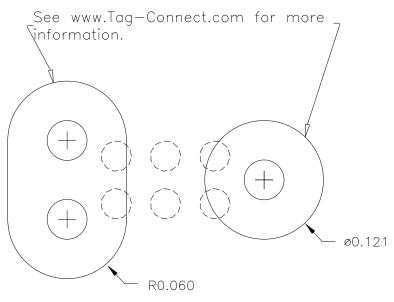
Do not allow solder paste on the contact pads. It is essential to eliminate any hole in the solder paste-mask (solder stencil) layer. If this is not possible make the contact pads thru-hole with finished hole size of 0.008" or less.

To avoid ordering confusion, please specify DNL in your BOM.

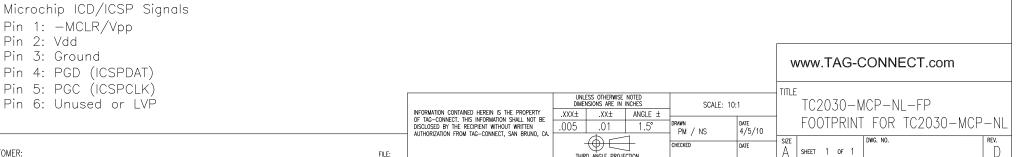
0.000 0.050 0.200 50 0.100 3X ø0.039 ±0.003 THRU ALIGNMENT PINS 0.040 0.025 2 6 6Х 0.000 -Ø0.031±0.004 CONDUCTIVE CONTACT 0.025 3 5 1 PADS 0.040 NO SOLDER PASTE!!

Optional copper pads allow soldering of s/steel alignment pins to underside of board for debugging use. Use stainless steel soldering flux and care to avoid melting the connector.

Alternatives include the TC2030-CLIP board that grips the s/steel pins from the underside or Mill-Max receptacles P/N 0295-0-15-XX-06-XX-10-0



OPTIONAL BOTTOM LAYER ALTERNATIVE - USE TC2030-CLIP BOARD



PCB TOP LAYER

"KEEP OUT"

AREA

CUSTOMER:

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Microchip:

TC2030-MCP-NL TC2030-CLIP-3PACK